CUI DEVICES

MODEL: HSB19-272718 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy
- black anodized finish



RoHS

MODEL

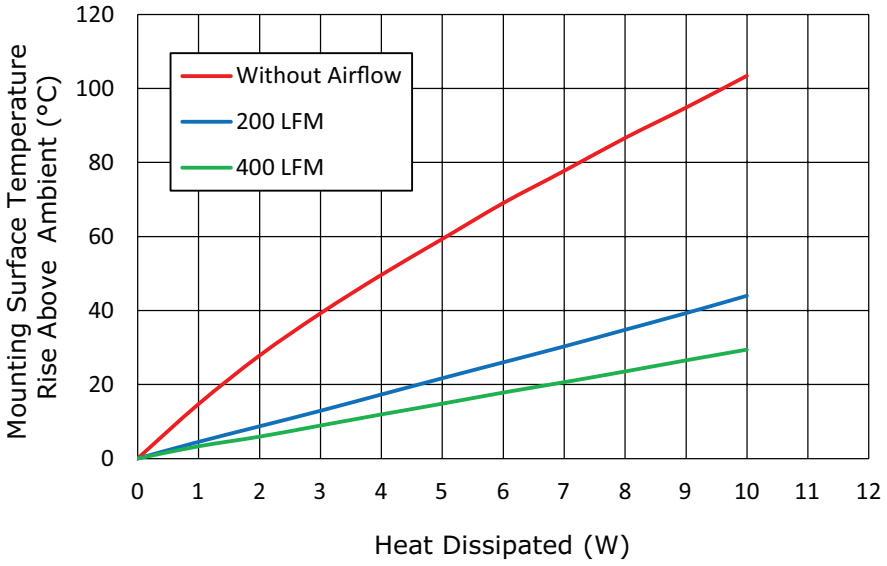
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSB19-272718	11.11	14.7	4.5	3.3	6.75

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	14.7	4.5	3.3
2	27.8	8.7	5.9
3	39.2	12.9	8.9
4	49.6	17.3	11.9
5	59.3	21.7	14.8
6	69.0	26.0	17.8
7	77.7	30.3	20.6
8	86.6	34.8	23.5
9	94.8	39.3	26.5
10	103.4	44.0	29.4

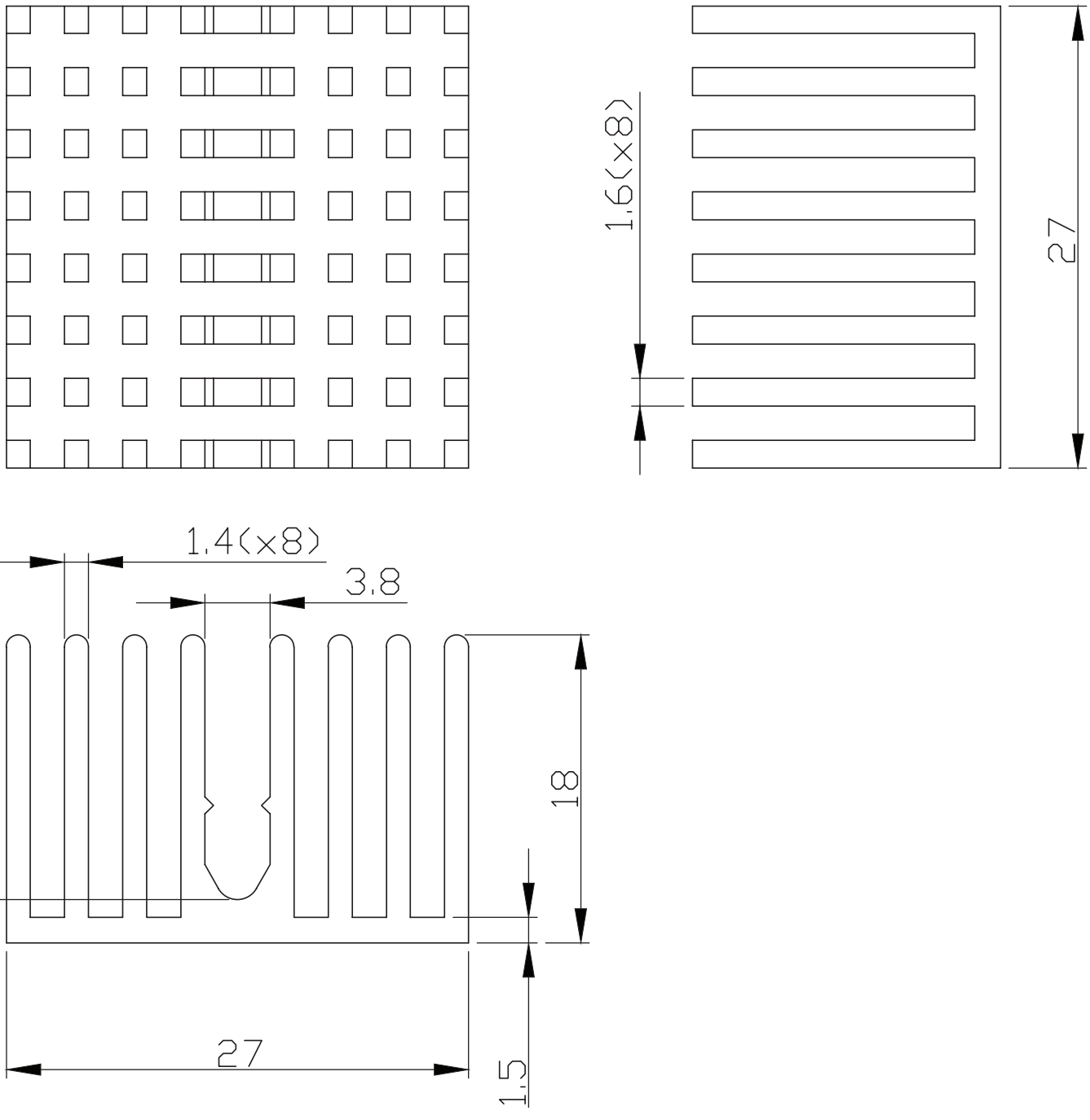
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	9.1 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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